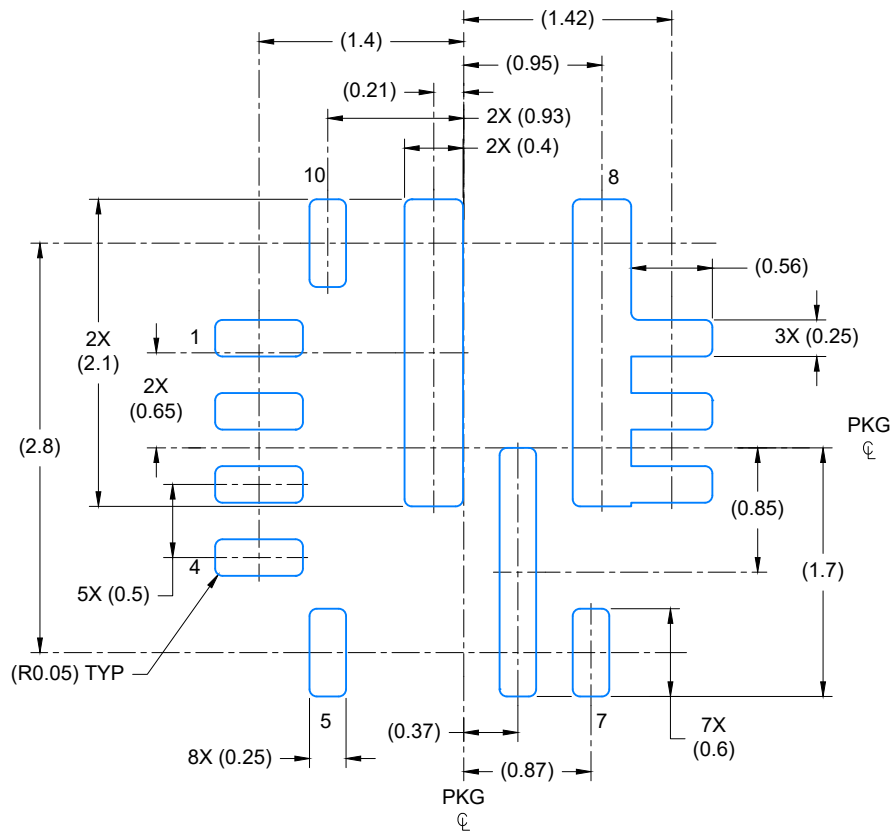
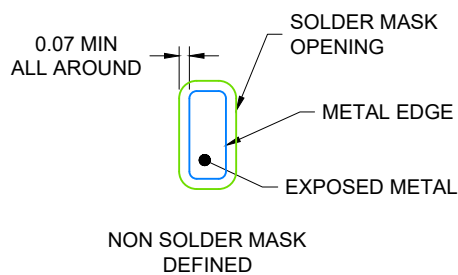


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.



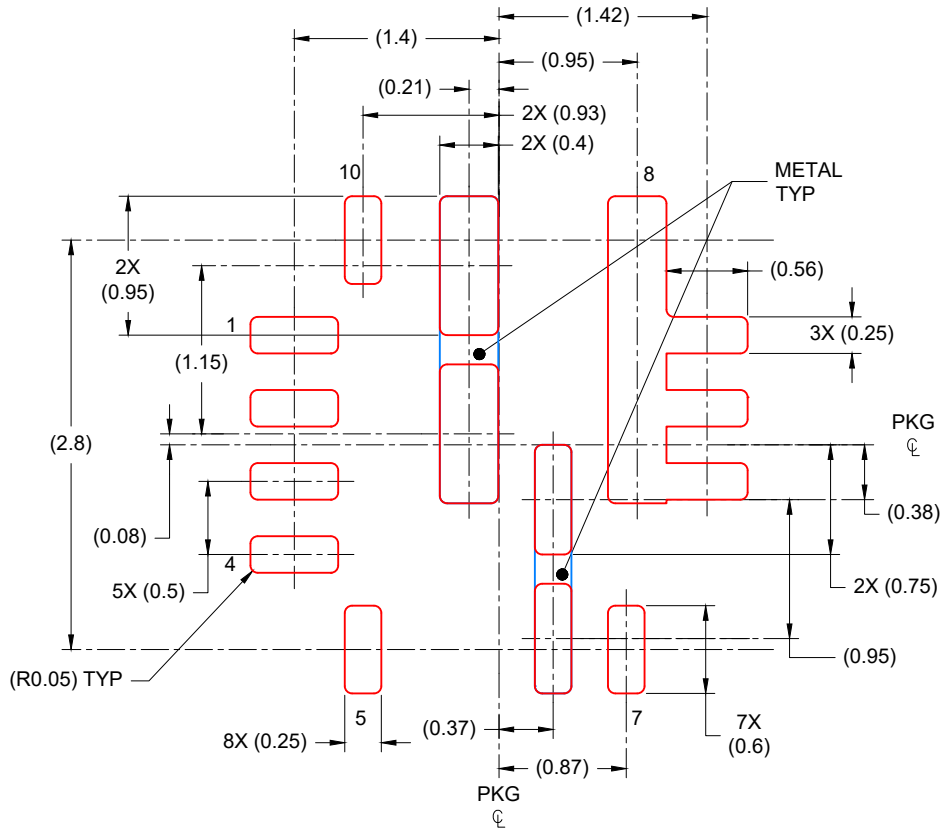
LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



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NOTES: (continued)

- 3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- 4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
 BASED ON 0.1 mm THICK STENCIL  
 EXPOSED PAD  
 PADS 6 and 9: 89% PRINTED COVERAGE BY  
 AREA  
 SCALE: 20X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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